

AP2012SF4C

2.0 x 1.25 mm Infrared Emitting Diode

DESCRIPTION

- SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes

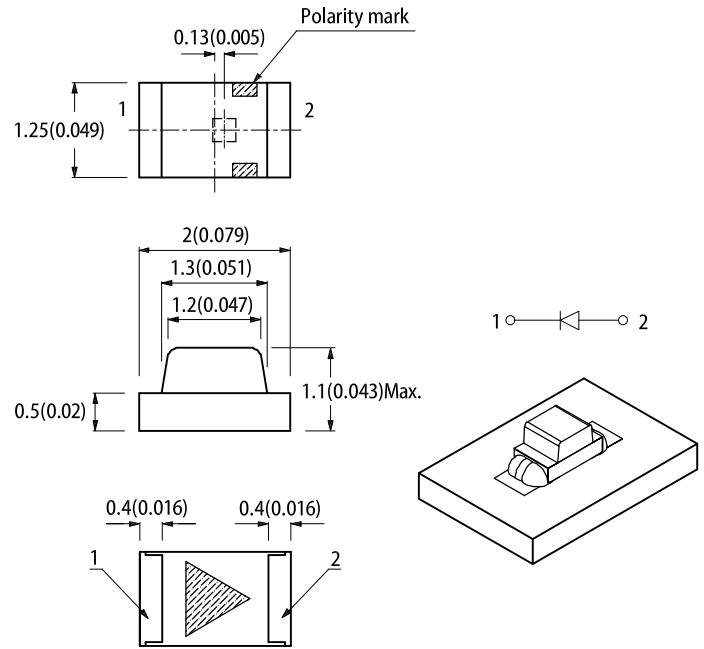
FEATURES

- 2.0 mm x 1.25 mm SMD LED, 1.1 mm thickness
- Mechanically and spectrally matched to the Phototransistor
- Package matches with photodetector AP2012P3C-P22
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

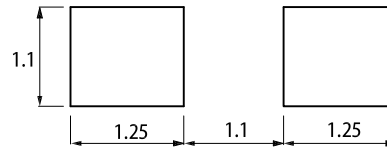
- Infrared Illumination for cameras
- Machine vision systems
- Surveillance systems
- Industrial electronics
- IR data transmission
- Remote control

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Po (mW/sr) @ 20mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
AP2012SF4C	Infrared (GaAlAs)	Water Clear	0.8	1.5	160°

Notes:
 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Radiant Intensity / luminous flux: +/- 15%.
 3. Radiant intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at $T_A=25^\circ\text{C}$

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission $I_F = 20\text{mA}$	λ_{peak}	Infrared	880	-	nm
Spectral Bandwidth at 50% Φ REL MAX $I_F = 20\text{mA}$	$\Delta\lambda$	Infrared	50	-	nm
Forward Voltage $I_F = 20\text{mA}$	$V_F^{[1]}$	Infrared	1.3	1.6	V
Reverse Current ($V_R = 5\text{V}$)	I_R	Infrared	-	10	μA
Temperature Coefficient of Wavelength $I_F = 20\text{mA}$, $-10^\circ\text{C} \leq T \leq 85^\circ\text{C}$	TC_λ	Infrared	0.3	-	$\text{nm}/^\circ\text{C}$
Temperature Coefficient of V_F $I_F = 20\text{mA}$, $-10^\circ\text{C} \leq T \leq 85^\circ\text{C}$	TC_V	Infrared	-1.3	-	$\text{mV}/^\circ\text{C}$

Notes:

1. Forward voltage: $\pm 0.1\text{V}$.
2. Wavelength value is traceable to CIE127-2007 standards.
3. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^\circ\text{C}$

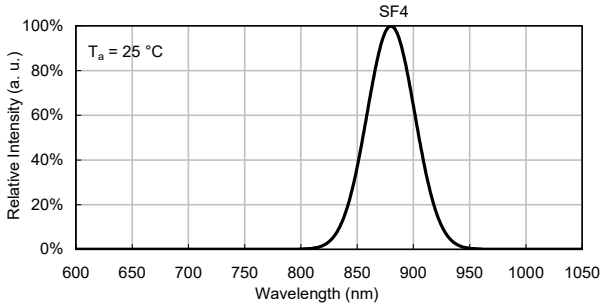
Parameter	Symbol	Value	Unit
Power Dissipation	P_D	85	mW
Reverse Voltage	V_R	5	V
Junction Temperature	T_j	125	$^\circ\text{C}$
Operating Temperature	T_{op}	-40 to +85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to +85	$^\circ\text{C}$
DC Forward Current	I_F	50	mA
Peak Forward Current	$I_{\text{FP}}^{[1]}$	1200	mA
Electrostatic Discharge Threshold (HBM)	-	8000	V
Thermal Resistance (Junction / Ambient)	$R_{\text{th JA}}^{[2]}$	420	$^\circ\text{C}/\text{W}$
Thermal Resistance (Junction / Solder point)	$R_{\text{th JS}}^{[2]}$	310	$^\circ\text{C}/\text{W}$

Notes:

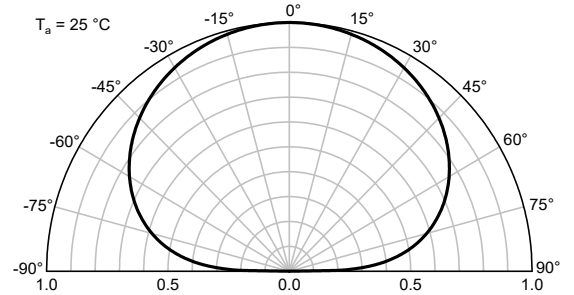
1. 1/100 Duty Cycle, 10 μs Pulse Width.
2. $R_{\text{th JA}}$, $R_{\text{th JS}}$ Results from mounting on PC board FR4 (pad size $\geq 16\text{ mm}^2$ per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

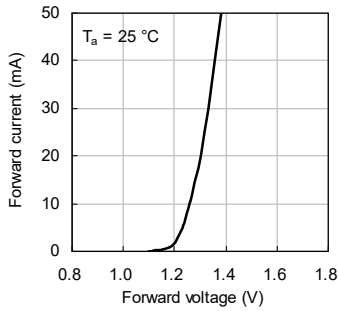


SPATIAL DISTRIBUTION

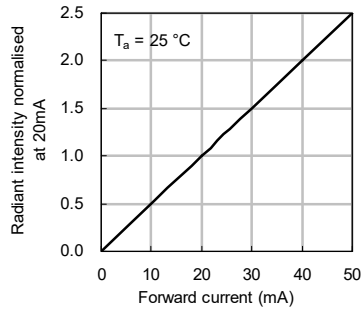


INFRARED

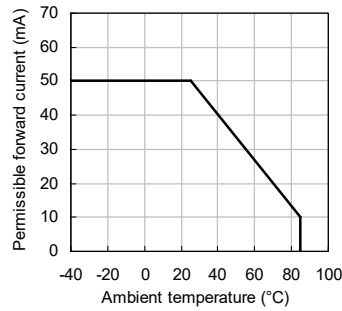
Forward Current vs. Forward Voltage



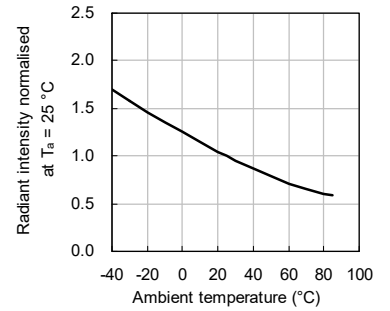
Radiant Intensity vs. Forward Current



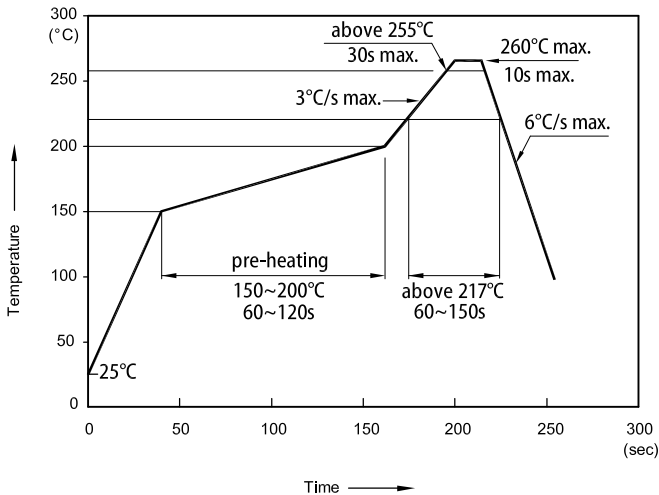
Forward Current Derating Curve



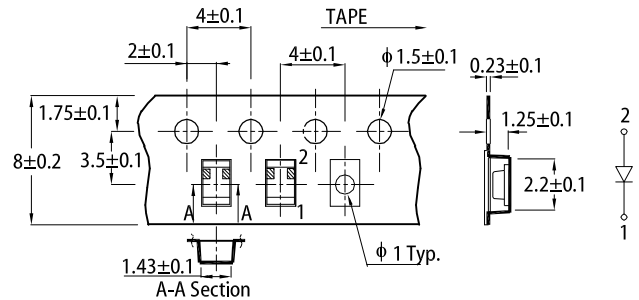
Radiant Intensity vs. Ambient Temperature



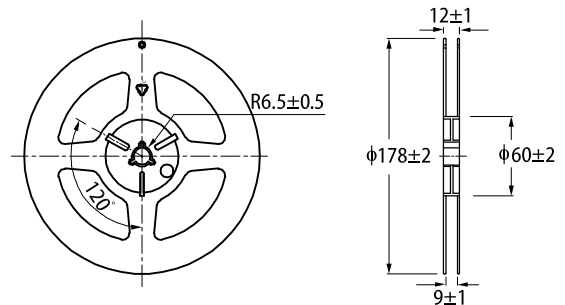
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)

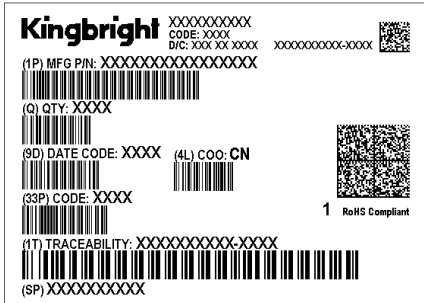
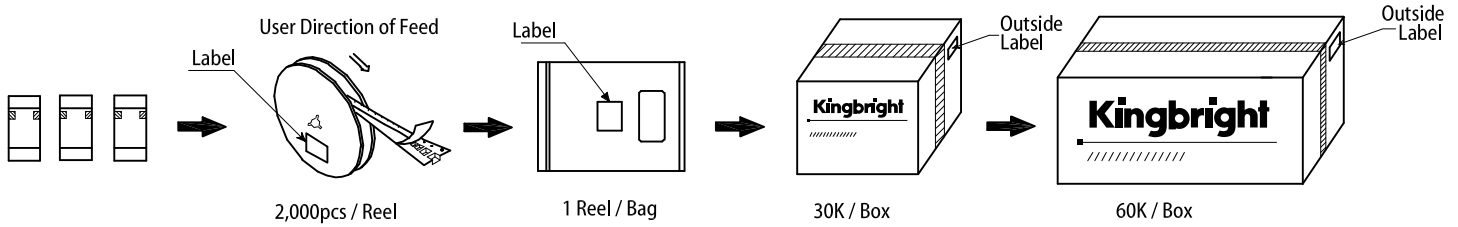


REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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